

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Previously Presented) A method for forming an assembly including semiconductor devices in stacked arrangement, comprising:  
applying substantially a predetermined volume of adhesive material to an active surface of a first semiconductor device; and  
positioning a second semiconductor device adjacent to the first semiconductor device, the adhesive material securing the second semiconductor device to the first semiconductor device and spacing a surface of the second semiconductor device a predetermined distance apart from the active surface of the first semiconductor device.
2. (Currently amended) The method of claim 1, wherein ~~the~~ applying comprises applying the adhesive material to the active surface of the first semiconductor device over which discrete conductive elements extend.
3. (Currently amended) The method of claim 2, wherein ~~the~~ positioning comprises positioning the second semiconductor device at least partially over at least one discrete conductive element of the discrete conductive elements.
4. (Currently amended) The method of claim 3, wherein ~~the~~ positioning comprises placing the second semiconductor device on the discrete conductive elements.
5. (Currently amended) The method of claim 4, wherein ~~the~~ applying comprises introducing the adhesive material between at least the first semiconductor device and the second semiconductor device.

6. (Currently amended) The method of claim 5, wherein ~~the~~ introducing includes forcing the surface of the second semiconductor device away from at least the first semiconductor device and spacing the surface of the second semiconductor device apart from the discrete conductive elements.

7. (Currently amended) The method of claim 5, wherein ~~the~~ introducing includes substantially encapsulating portions of the discrete conductive elements located over the active surface of at least the first semiconductor device.

8. (Original) The method of claim 5, further comprising:  
substantially hardening the adhesive material to at least a semisolid state to space the active surface of at least the first semiconductor device substantially the predetermined distance apart from the surface of the second semiconductor device.

9. (Currently amended) The method of claim 8, wherein ~~the~~ substantially hardening comprises substantially curing the adhesive material.

10. (Currently amended) The method of claim 8, wherein ~~the~~ substantially hardening includes decreasing a distance the active surface of the first semiconductor device is spaced apart from the surface of the second semiconductor device from substantially a set distance to substantially the predetermined distance.

11. (Currently amended) The method of claim 1, wherein ~~the~~ applying comprises applying the adhesive material to the active surface of at least the first semiconductor device before the positioning.

12. (Currently amended) The method of claim 8, further comprising, upon the positioning, using the adhesive material to draw the second semiconductor device toward at least the first semiconductor device until at least the first semiconductor device and the second semiconductor device are spaced substantially a set distance apart from one another.

13. (Original) The method of claim 1, further comprising:  
substantially hardening the adhesive material to at least a semisolid state to space the surface of at least the first semiconductor device substantially the predetermined distance apart from the surface of the second semiconductor device.

14. (Currently amended) The method of claim 13, wherein the substantially hardening comprises substantially curing the adhesive material.

15. (Currently amended) The method of claim 13, wherein the substantially hardening includes decreasing a distance the active surface of at least the first semiconductor device is spaced apart from the surface of the second semiconductor device from substantially a set distance to substantially the predetermined distance.

16. (Original) A method for forming a multi-chip module, comprising:  
providing a substrate including a plurality of contact areas;  
establishing electrical communication between the substrate and a first semiconductor device;  
applying substantially a predetermined volume of adhesive material onto at least a surface of the first semiconductor device; and  
positioning a second semiconductor device adjacent to the first semiconductor device, the adhesive material securing the second semiconductor device to the first semiconductor device and spacing the surface of the second semiconductor device substantially a predetermined distance apart from the surface of the first semiconductor device.

17. (Currently amended) The method of claim 16, wherein ~~the~~ applying is effected following ~~the~~ establishing.

18. (Currently amended) The method of claim 17, wherein ~~the~~ positioning follows ~~the~~ applying.

19. (Currently amended) The method of claim 17, wherein ~~the~~ applying follows ~~the~~ positioning.

20. (Currently amended) The method of claim 17, wherein ~~the~~ positioning comprises positioning the second semiconductor device over the first semiconductor device and at least partially over at least one discrete conductive element protruding above the surface of the first semiconductor device.

21. (Currently amended) The method of claim 16, wherein ~~the~~ establishing electrical communication comprises:  
placing discrete conductive elements between bond pads of the first semiconductor device and corresponding contact areas of the plurality of contact areas of the substrate to electrically connect the bond pads to the corresponding contact areas, the discrete conductive elements extending partially over the surface of the first semiconductor device.

22. (Currently amended) The method of claim 21, wherein ~~the~~ placing discrete conductive elements comprises at least one of wire bonding bond pads to corresponding contact areas, tape-automated bonding bond pads to corresponding contact areas, and thermocompression bonding leads to bond pads.

23. (Original) The method of claim 21, further comprising:  
encapsulating at least portions of the first semiconductor device, the second semiconductor device, the discrete conductive elements, and the substrate.

24. (Currently amended) The method of claim 16, wherein ~~the positioning~~ the second semiconductor device comprises positioning the second semiconductor device onto the predetermined volume of adhesive material.

25. (Currently amended) The method of claim 16, further comprising using the predetermined volume of adhesive material to draw the second semiconductor device toward the first semiconductor device with the second semiconductor device spaced substantially a set distance apart from the first semiconductor device.

26. (Currently amended) The method of claim 16, wherein ~~the introducing~~ applying substantially the predetermined volume of adhesive material is effected following positioning of the second semiconductor device.

27. (Currently amended) The method of claim 26, wherein ~~the introducing~~ applying substantially the predetermined volume of adhesive material comprises introducing adhesive material between the first semiconductor device and the second semiconductor device.

28. (Currently amended) The method of claim 27, wherein ~~the introducing~~ electrically isolates discrete conductive elements protruding from the first semiconductor device from the surface of the second semiconductor device.

29. (Currently amended) The method of claim 27, wherein ~~the introducing~~ pushes the second semiconductor device away from the first semiconductor device to substantially the predetermined distance.

30. (Currently amended) The method of claim 27, wherein ~~the introducing~~ coats at least portions of discrete conductive elements located adjacent to the surface of the second semiconductor device.

31. (Original) The method of claim 16, further comprising:  
substantially hardening the adhesive material to at least a semisolid state to space the surface of  
the first semiconductor device apart from the surface of the second semiconductor device  
by substantially the predetermined distance.

32. (Currently amended) The method of claim 31, wherein ~~the~~ substantially  
hardening comprises substantially curing the adhesive material.

33. (Currently amended) The method of claim 31, further comprising[:]  
decreasing a distance the surface of the first semiconductor device is spaced apart from the  
surface of the second semiconductor device from substantially a set distance to  
substantially the predetermined distance by ~~the~~ substantially hardening.